

**Response Under 37 C.F.R. § 1.116**

**Expedited Procedure**

**Examining Group 2841**

Application No. 10/581,880

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In Reply to USPTO Correspondence of July 21, 2008

Attorney Docket No. 1217-052989

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims**

1-14. (Cancelled)

15. (Currently Amended) The process according to claim 1 A process for manufacturing a printed wiring board, which process comprises preparing a laminated film comprising a polyimide film and a copper layer provided on at least one surface of the polyimide film with a sputtered metal layer formed from nickel, chrome or an alloy thereof in between, selectively etching the copper layer and the sputtered metal layer of the laminated film to produce a wiring pattern, treating the laminated film with a first treatment liquid capable of dissolving nickel of the sputtered metal layer, and treating with a second treatment liquid capable of dissolving chrome of the sputtered metal layer and also capable of eliminating the sputtered metal layer in the polyimide film to remove a superficial surface of the polyimide film exposed from the wiring pattern together with the residual sputtered metals in the superficial surface, wherein the laminated film is treated with the first treatment liquid including mixtures of approximately 5 to 15 % by weight each of sulfuric acid and hydrochloric acid at temperatures of 30 to 55° C over a period of 2 to 40 seconds and further treated with the second treatment liquid including aqueous potassium permanganate/KOH solution having the potassium permanganate concentration of 10 to 60 g/l at temperatures of 40 to 70° C over a period of 10 to 60 seconds.